

OL-NVT4555UK

wafer level chip-scale package, 12 balls; 1.19 x 1.62 x 0.56 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	26-2-2013

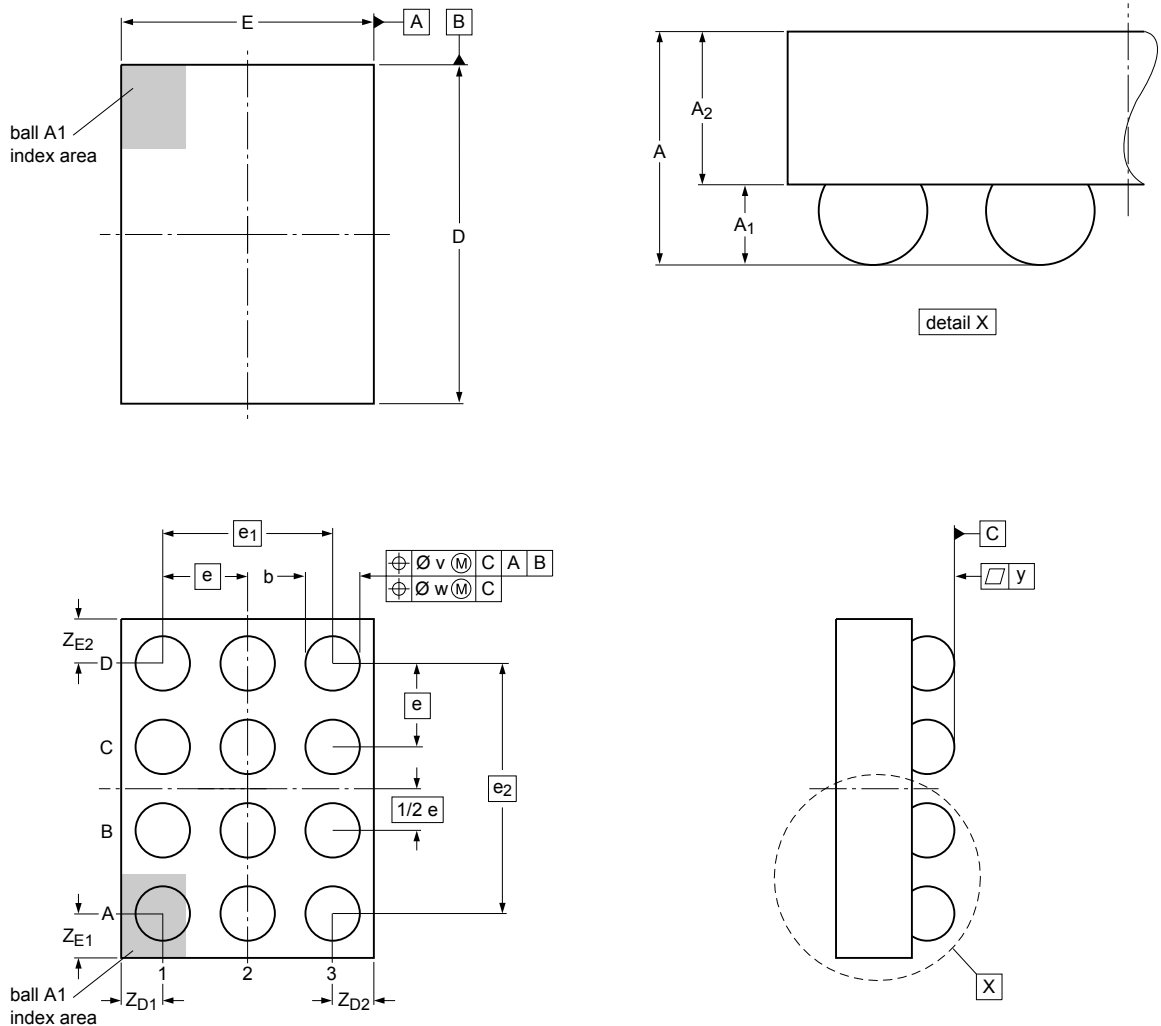
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.59	-	1.62	1.65	mm
E	package width	1.16	-	1.19	1.22	mm
A	seated height	0.52	-	0.56	0.6	mm
A ₂	package height	0.335	-	0.36	0.385	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	12	-	



2. Package outline

WLCSP12: wafer level chip-scale package, 12 balls; 1.19 x 1.62 x 0.56 mm NVT4555UK



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	Z _{D1}	Z _{D2}	Z _{E1}	Z _{E2}
max	0.60	0.23	0.385	0.29	1.65	1.22							0.225	0.225	0.24	0.24
mm nom	0.56	0.20	0.360	0.26	1.62	1.19	0.4	0.8	1.2	0.15	0.05	0.05	0.195	0.195	0.21	0.21
min	0.52	0.17	0.335	0.23	1.59	1.16							0.165	0.165	0.18	0.18

wlcspl2_nvt4555uk_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NVT4555UK					-13-02-04- 13-02-26

Fig. 1. Package outline WLCSP (OL-NVT4555UK)

3. Legal information

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